



3.0A SCHOTTKY BARRIER RECTIFIER

Product Summary

B350BE/B350CE B360BE/B360CE

V _{RRM} (V)	I _O (A)	V _F Max (V) @ +25°C	I _R Max (mA) @ +25°C
50	3	0.65	0.1
60	3	0.65	0.2

Description and Applications

The Schottky rectifier providing low V_F and excellent reverse leakage stability at high temperatures, this device is ideal for use in general rectification applications such as:

- Boost Diode
- Blocking Diode
- Recirculating Diode

Features and Benefits

- Reduced Low Forward Voltage Drop (V_F); Better Efficiency and Cooler Operation
- Reduced High-Temperature Reverse Leakage; Increased Reliability against Thermal Runaway Failure in High Temperature Operation
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: SMB, SMC
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Polarity: Cathode Band
 - Weight: SMB- 0.093 grams (Approximate) SMC- 0.21 grams (Approximate)

SMB/SMC



Top View



Bottom View

Ordering Information (Note 4)

Part Number	Case	Packaging
B3XXBE-13	SMB	3,000/Tape & Reel
B3XXCE-13	SMC	3,000/Tape & Reel

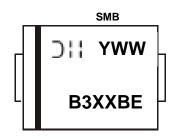
Notes: 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

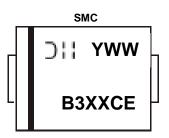
Marking Information



B3XXBE = Product Type Marking Code, ex: B350BE Dill = Manufacturers' Code Marking YWW = Date Code Marking Y = Last Digit of Year (ex: 7 for 2017) WW = Week Code (01 to 53)



Marking Information (Cont.)



B3XXCE = Product Type Marking Code, ex: B350CE DIII = Manufacturers' Code Marking YWW = Date Code Marking Y = Last Digit of Year (ex: 7 for 2017) WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load. derate current by 20%.

Characteristic	Symbol	B350BE/B350CE	B360BE/B360CE	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} Vrwm V _{RM}	50	60	V
Average Rectified Output Current	lo	:	3	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	8	0	А

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	SMB	R _{θJA}	90	°C/W
	SMC		70	
Typical Thermal Resistance Junction to Case (Note 5)	SMB SMC	$R_{ extsf{ heta}JC}$	50 30	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	V _F		0.55 0.52	0.65	V	I _F = 3A, T _J = +25°C I _F = 3A, T _J = +125°C
Leakage Current (Note 6) B350BE/ B350CE B360BE/ B360CE	I _R		 25	0.1 0.2 —	mA	$V_{R} = 50V, T_{J} = +25^{\circ}C$ $V_{R} = 60V, T_{J} = +25^{\circ}C$ $V_{R} = 60V, T_{J} = +125^{\circ}C$
Typical Capacitance	CT	—	110	—	pF	V _R = 4.0V, f = 1MHz

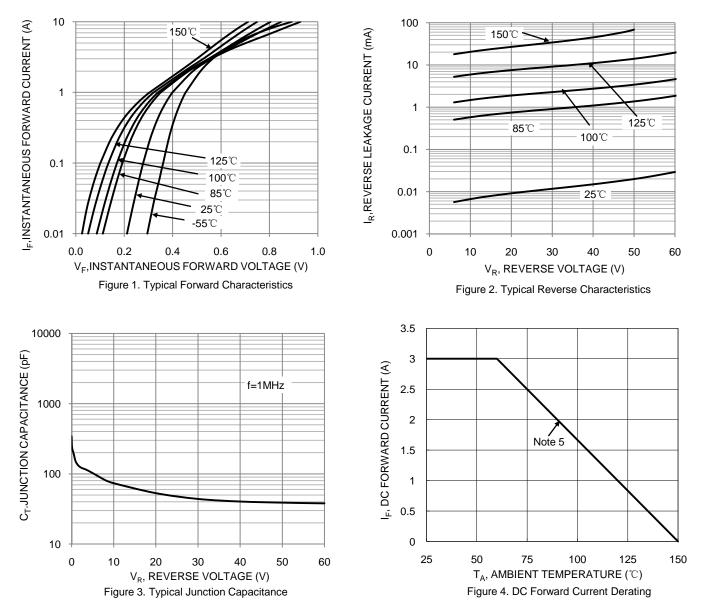
Notes:

5. Device mounted on FR-4 substrate, 0.4"*0.5", 2oz, single-sided, PC boards with 0.2"*0.25" copper pad.

6. Short duration pulse test used to minimize self-heating effect.



B350BE-B360BE B350CE-B360CE

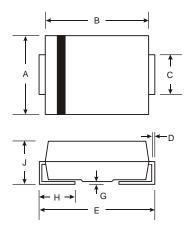




Package Outline Dimensions

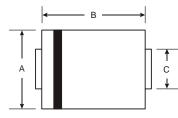
Please see http://www.diodes.com/package-outlines.html for the latest version.

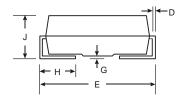
SMB



SMB				
Dim	Min	Max		
Α	3.30	3.94		
В	4.06	4.57		
С	1.96	2.21		
D	0.15	0.31		
E	5.00	5.59		
G	0.05	0.20		
Н	0.76	1.52		
J	2.00	2.50		
All Dimensions in mm				

SMC





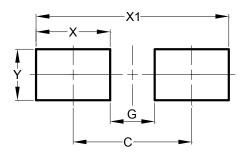
SMC		
Dim	Min	Max
Α	5.59	6.22
В	6.60	7.11
С	2.75	3.18
D	0.15	0.31
E	7.75	8.13
G	0.10	0.20
н	0.76	1.52
J	2.00	2.50
All Dimensions in mm		



Suggested Pad Layout

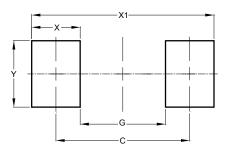
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SMB



Dimensions	Value (in mm)
С	4.30
G	1.80
Х	2.50
X1	6.80
Y	2.30

SMC



Dimensions	Value	
Dimensions	(in mm)	
С	6.90	
G	4.40	
Х	2.50	
X1	9.40	
Y	3.30	



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